



Dicing Saws

Fully Automatic Single Spindle Dicing Saws

72XXseries

7222 is used for cutting 8-inch wafers and materials such as PZT and IR glass.

7232 is used for cutting large substrates and multi-layered substrates.

7224 is used for cutting 8-inch thick glass, ceramics, and other hard materials.

7234 is used for cutting 12-inch thick glass, ceramics, and other hard materials.

7302 is an advanced version of 7232 with a larger chuck size of 12" × 10".

7304 is an advanced version of 7234 with a larger chuck size of 12" × 10".

Machine features

- Efficient wafer handling system
- Blade wear prediction algorithm to reduce height measurement time and increase hourly output
- Continuous digital zoom vision system
- Atomized wafer cleaning technology, with excellent process effect.



72XXseries						
	7222	7232	7224	7234	7302	7304
Workpiece Size	Ø8"	Ø12"	Ø8"	Ø12"	12" × 9" or Ø12"	12" × 9"
Spindle	60K rpm/1.8kW or 2.2kW		30K rpm/2.5kW	60K rpm/1.8kW		30K rpm/2.5kW
Blade Size	2"~3"		4"~5"		2"~3"	4"~5"
Dimensions	965×1785×1700	1100×1785×1700	965×1460×1700	1100×1785×1700		
Weight	1200 kg	1350 kg	1200 kg	1350 kg		

Y-axis	Controller	Linear encoder/Y-axis
	Resolution	0.1 μm
	Cumulative Accuracy	1.5 μm
	Indexing Accuracy	1.0 μm
X-axis		Air Slide
Z-axis	Repeatability	1.0 μm
	Maximum Travel	30 mm (2.188" Blade Outer Diameter)
	Resolution	0.2 μm
θ-axis	Repeatability	4 arc-sec
	Stroke	380°
Cleaning Station		Complete Rinse and Dry Cycle
	Rotation Speed	100~2000 rpm
	Cleaning Method	Atomized cleaning capabilities
Electrical		200~240VAC, 50-60Hz, single phase